

Title (en)

PADS FOR CMP AND POLISHING SUBSTRATES

Title (de)

KISSEN FÜR CMP UND POLIERSUBSTRATE

Title (fr)

TAMPONS POUR PLANARISATION CHEMICO-MECANIQUE ET POLISSAGE DE SUBSTRATS

Publication

EP 1465753 A2 20041013 (EN)

Application

EP 02776348 A 20021029

Priority

- US 0234617 W 20021029
- US 34081901 P 20011029
- US 2008201 A 20011211

Abstract (en)

[origin: WO03038862A2] Pads and methods of making the pads for applications such as polishing substrates and chemical mechanical planarization of substrates are provided. The pads are substantially porous and substantially hard for improved polishing and planarization properties. Pads according to some embodiments of the present invention have beneficial properties like those of standard technology porous pads and beneficial properties like those of standard technology hard pads.

IPC 1-7

B24D 3/32

IPC 8 full level

B24B 37/24 (2012.01); **B24D 11/00** (2006.01); **B24D 13/14** (2006.01); **D04H 1/42** (2006.01); **D04H 1/46** (2006.01); **D06M 15/564** (2006.01); **H01L 21/304** (2006.01)

CPC (source: EP KR US)

B24B 37/24 (2013.01 - EP US); **B24D 3/32** (2013.01 - KR); **B24D 11/001** (2013.01 - EP US)

Citation (search report)

See references of WO 03038862A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR IE IT LI LU MC NL PT SE SK TR

DOCDB simple family (publication)

WO 03038862 A2 20030508; **WO 03038862 A3 20040311**; AU 2002342182 A1 20030512; EP 1465753 A2 20041013; JP 2005518286 A 20050623; KR 20050040838 A 20050503; US 2003100250 A1 20030529

DOCDB simple family (application)

US 0234617 W 20021029; AU 2002342182 A 20021029; EP 02776348 A 20021029; JP 2003541020 A 20021029; KR 20047006435 A 20040429; US 2008201 A 20011211